



# WPA25-3560C

## 2.4 – 2.6 GHz 35W POWER AMPLIFIER

REV B  
December 2015

### Key Features



- 50 Ohm Impedance
- 2.4 ~ 2.6 GHz
- 2.0 dB Noise Figure
- 60.0 dBm Output IP<sub>3</sub>
- 42.0 dB Gain
- 45.5 dBm P<sub>sat</sub>
- 1.25:1 VSWR
- Single Power Supply
- >34 years MTBF
- Unconditional Stable
- Infinite Load VSWR Protection
- RoHS Compliant

### Product Description

WPA25-3560C is integrated with WanTcom proprietary power amplifier technology, high frequency micro electronic assembly techniques, and high reliability design to realize optimum low noise figure, wideband, high linearity, and unconditional stable performances together. With single +28V operation, the amplifier has optimal input and output matching in the specified frequency range at 50-Ohm impedance system. The amplifier has standard SMA connectorized WP-1M clear plated housing.

The amplifier is designed to meet the rugged standard of MIL-STD-202g.

**Additional heat sink is required for continuous operation!**

### Specifications

Summary of the electrical specifications WPA25-3560C at room temperature

Index	Testing Item	Symbol	Test Constraints	Min	Nom	Max	Unit
1	Gain	S <sub>21</sub>	2.4 – 2.6 GHz		42		dB
2	Gain Variation	ΔG	2.4 – 2.6 GHz		+/- 1.0	+/-1.3	dB
3	Input VSWR	SWR <sub>1</sub>	2.4 – 2.6 GHz		1.25:1	1.4:1	Ratio
4	Output VSWR	SWR <sub>2</sub>	2.4 – 2.6 GHz		1.25:1	1.5:1	Ratio
5	Reverse Isolation	S <sub>12</sub>	2.4 – 2.6 GHz	50	60		dB
6	Noise Figure	NF	2.4 – 2.6 GHz		2.0		dB
7	Output IP <sub>3</sub>	IP <sub>3</sub>	P <sub>o</sub> = 34 dBm each tone, 1 MHz separation	56	60		dBm
8	Output Saturated Power	P <sub>sat</sub>	2.4 – 2.6 GHz	25	35		W
9	Error Vector Magnitude	EVM	P <sub>o</sub> = 37 dBm		2		%
10	Current Consumption	I <sub>dd</sub>	V <sub>dd</sub> = +28 V, no RF signal at input		0.75		A
11	Power Supply Voltage	V <sub>dd</sub>		+26	+28	+30	V
12	Thermal Resistance	R <sub>th,c</sub>	Last stage power transistor, junction to case			2.0	°C/W
13	Operating Temperature	T <sub>o</sub>	Housing base temperature	-40		+85	°C
14	Maximum CW RF Input Power	P <sub>IN,MAX</sub>	2.4 – 2.6 GHz			30	dBm
15	Output Maximum Load Mismatch	SWR, load	2.4 – 2.6 GHz			∞	Ratio
16	Enable Control Function	V <sub>EN</sub>	ON	3.7	5	12	V
			OFF	0		0.2	V

### Applications

- Mobile Infrastructures
- WiMax
- Fixed Wireless

### Ordering

Model	WPA25-3560C
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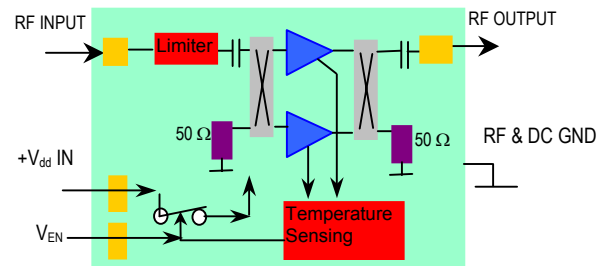


### Absolute Maximum Ratings

Parameters	Units	Ratings
DC Power Supply Voltage	V	-0.5, +32
Drain Current	A	4.5
Total Power Dissipation	W	150
CW RF Input Power	dBm	30
Channel Temperature	°C	150
Storage Temperature	°C	-55 ~ 150
Operating Temperature	°C	-40 ~ +85
Thermal Resistance	°C/W	2.0 °C/W*

Operation of this device above any one of these parameters may cause permanent damage.  
\*One of the last stage power transistor, V<sub>dd</sub> = 28V, I<sub>d</sub> = 2.0A Max.

### Functional Block Diagram



Specifications and information are subject to change without notice.

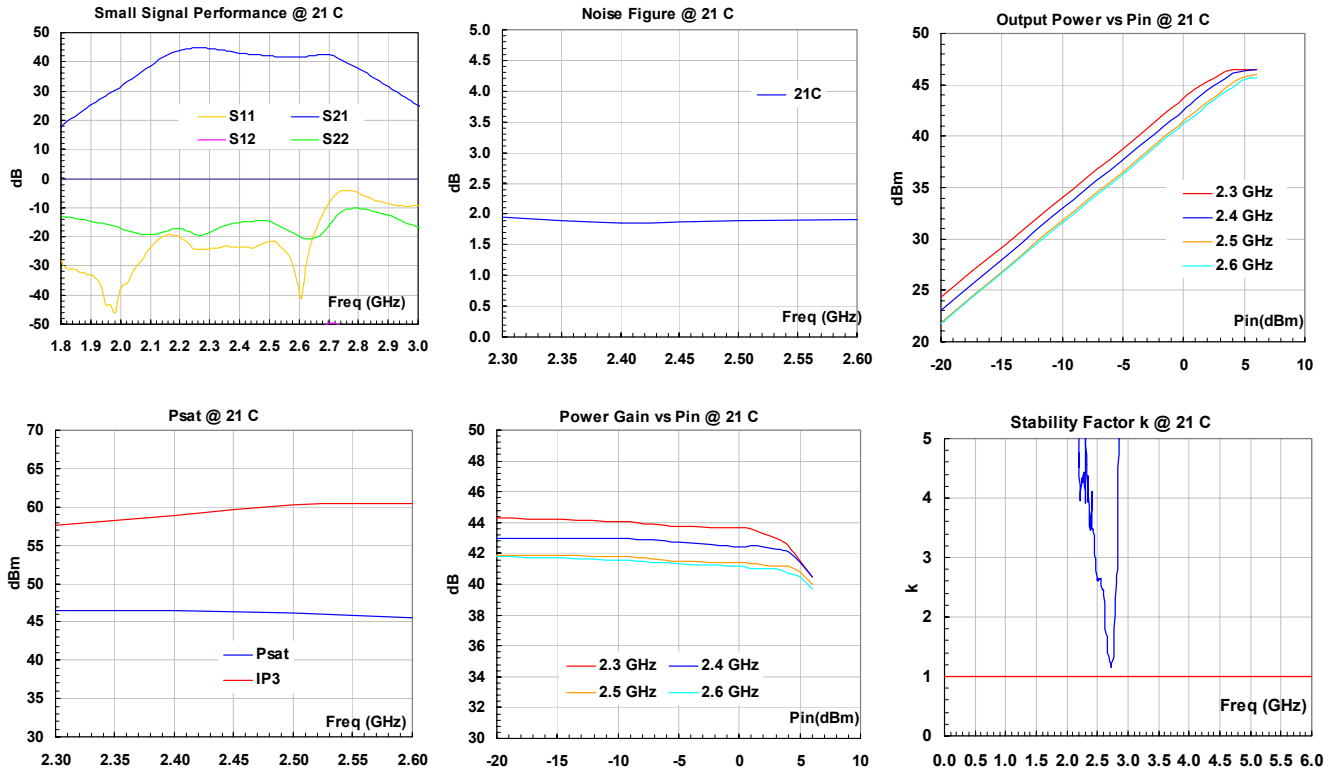


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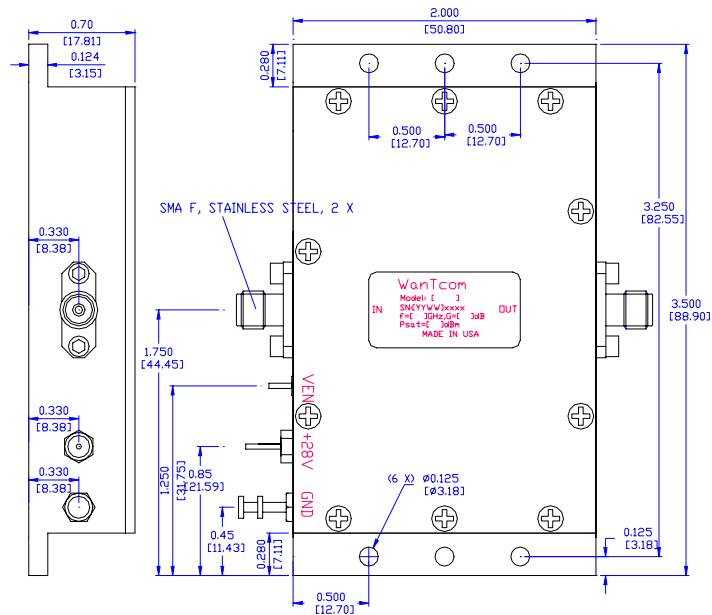
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### Typical Data



### Outline, WP-1M Housing

UNITS: INCH [mm]  
 BODY: Aluminum Alloy  
 Finish: Clear Plating  
 RF Connector: SMA F Stainless  
 +28V DC I/O: Feedthru



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## **Application Notes:**

### **A. SMA Torque Wrench Selection**

Always use a torque wrench with 5 ~ 6 inch-lb coupling torque setting for mating the SMA cables to the amplifier. Never use torque more than 8 inch-lb wrench for tightening the mating cable to the connector. Otherwise, the permanent damage will occur to the SMA connectors of the amplifier. 8710-1582 (5 inch-lb) is one of the ideal torque wrench choice from Agilent Technology.

### **B. Mounting the Amplifier**

Use six pieces of #4-40 with longer than 3/8" screws for mounting the amplifier on a metal-based heat sink. Flat and spring washers are needed to prevent the screw loosening during the shock and vibration. Always use the appropriate torque setting of the power screwdriver to mount them. Proper heat sink is required for continuous operation. T-gon thermal film or other thermal compound is required between the bottom of the PA and heat sink for better heat transference.

### **C. Testing**

Due to high output RF power of more than 30W and high gain, damage can occur to a test equipment if the input power level to the PA is set too high with no high power attenuator between the output of the PA and input of the test equipment. For example, A Keysight/Agilent VNA has default 0 dBm power output at Port 1, which will generate more than 10W RF power at the output of PA.

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